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conc.

for electrically contacting a contact on the die, a conductive trace on the film in electrical communication with the bump for conducting the test signals to the bump, and an electrical connector on the film in electrical communication with the trace configured for electrical connection to the test circuitry, the trace extending continuously on the film from the connector to the bump and with the connector, the trace and the bump providing a direct electrical path from the test circuitry to the contact, and with a portion of the film and the connector extending beyond a confine of the fixture;

providing a compressible member configured for placement between the first plate and the second plate to bias the die against the die contact member;

placing the die on the first plate with the bump in physical and electrical contact with the contact;

securing the second plate to the first plate with the compressible member compressed therebetween to bias the bump against the contact; and

electrically connecting the connector to the test circuitry.

53. (added) The method of claim 52 wherein the contact on the die comprises a bondpad.


54. (added) The method of claim 52 wherein the film comprises polyimide and the bump comprises solder.

### REMARKS

Claims 1-33 have been canceled and claims 34-54 have been added. The added claims are directed to the embodiment shown in Figure 8. In this embodiment, TAB tape 143 (referred to as "plastic film" in the claims) includes contacts (e.g., contacts 47-Figure 2) that make electrical connections with contacts on the die on the die 21 (e.g.,

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